

Chip-Scale Photonic Logic and Switching with InGaAsP/InP Microresonators

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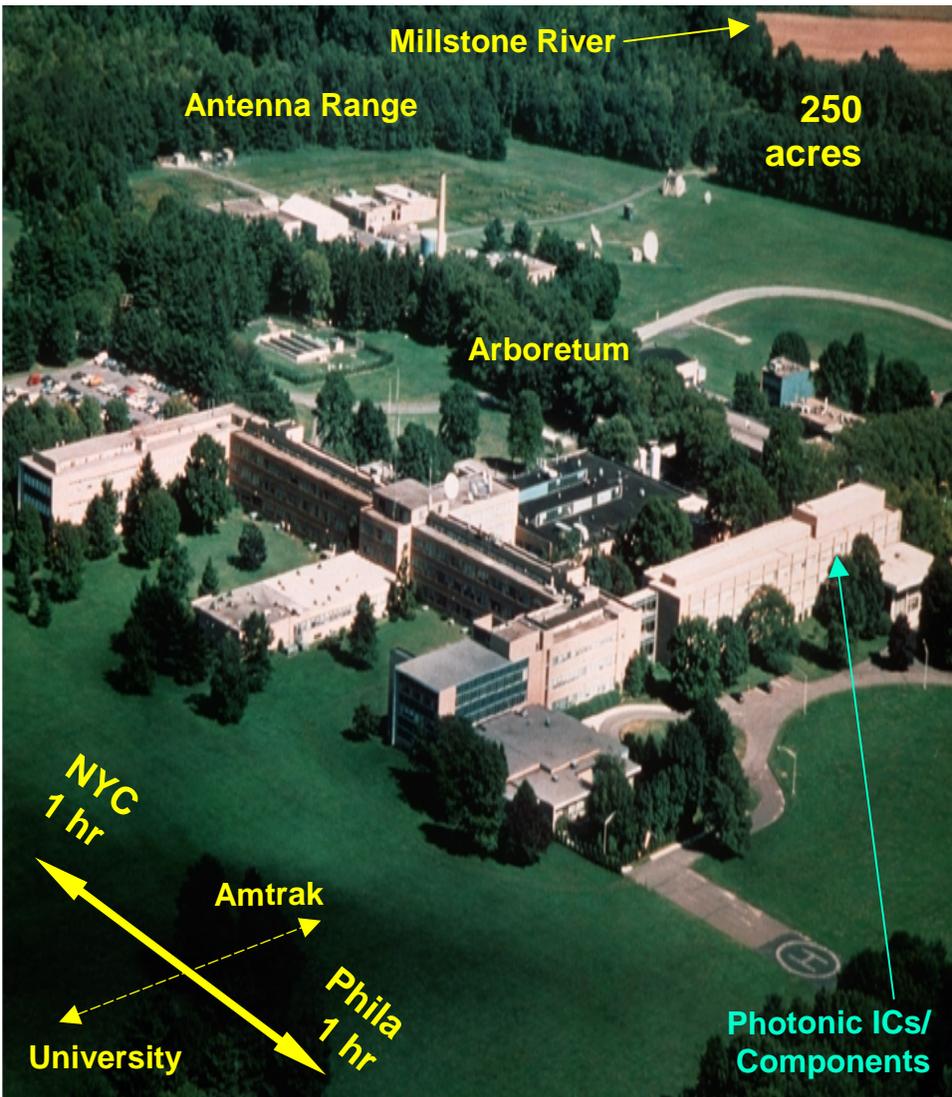
DARPA/MTO Workshop on *Data in the Optical Domain*

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Arlington, VA

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Sarnoff Corporation: Photonic ICs & Components



- Princeton, New Jersey location
- Former RCA Labs (est. 1942)
- Subsidiary of SRI International
- Our business is innovation services
- ~50/50% Gov't-Commerical customers
- 50 years of photonics
- The Sarnoff Model
 - Technology Transition
 - Sarnoff Spin Out companies
 - 3 Photonics Companies
 - More coming
 - Reward Employees
 - Equity, Royalties
 - Continue to keep “A-team” available for the most advanced development

The Sarnoff Perspective on Diode Laser Materials: first Threshold, then Power, now Efficiency

- 1960s & 70s
 - Basic Materials
- 1980s-1994
 - CDH-LOC; CSP
 - MIC Arrays (PILOT)
- 1989-95
 - MOPA
 - Tapered Amplifier MOPA
- 1994-2000
 - Broadened WG

A Brief History of Laser Diode Materials

First Era (1964-1982):
Increase Temperature

Second Era (1982-2000):
Increase Power

*Third Era (2000-2018?):
Increase Efficiency*

**RCA/Sarnoff and SRI/Sarnoff Pioneers Have Set
the Standards for Laser Performance at
Wavelengths from 0.8 to 3 μm**

Sarnoff Photonics: Capabilities

- **Highest efficiency, low noise diode laser materials**
- **Highest efficiency InP 1550 nm modulator materials (10x better than current literature)**
- **Lowest loss waveguides (0.1 cm^{-1})**
- **Deeply etched waveguides**
- **Lowest noise InP-based mode-locked lasers**
 - **Highest powers (165 W)**
 - **Lowest noise (fsec jitter, $1e-4$ amplitude noise)**
 - **Shortest pulses (200 fsec)**
 - **Coding technologies**
- **First 894 nm VCSEL (Atom. Clock)**
- **Laser conjugator devices**
- **Bistable devices**
- **Mid-IR Lasers**
- **Unique source of AlGaAs DFBs (791, 830 nm)**
- **Narrowest linewidth DFB lasers (10 - 100 kHz Gaussian & Lorentzian linewidths)**
- **Advanced InP ring microresonator & integration**
 - **Q of 20,000 demonstrated**
 - **Few GHz bandwidth**
 - **Lateral = simple fabrication**
- **Highest efficiency thermophotovoltaic cells (not released for publication)**
- **Exciting *new* 1550 nm platform integration technology (not released for publication)**

Sarnoff Facilities

- **Standard processing**
- **Facet coating to 1e-4**
- **E-beam lithography**
- **Holographic gratings**

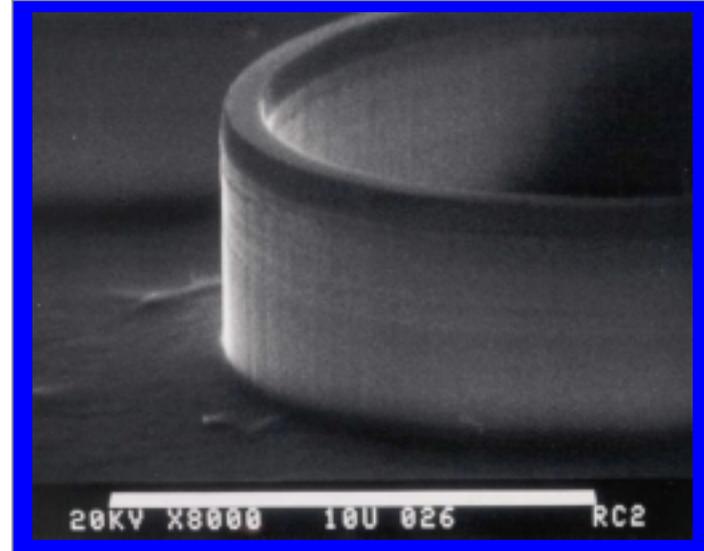
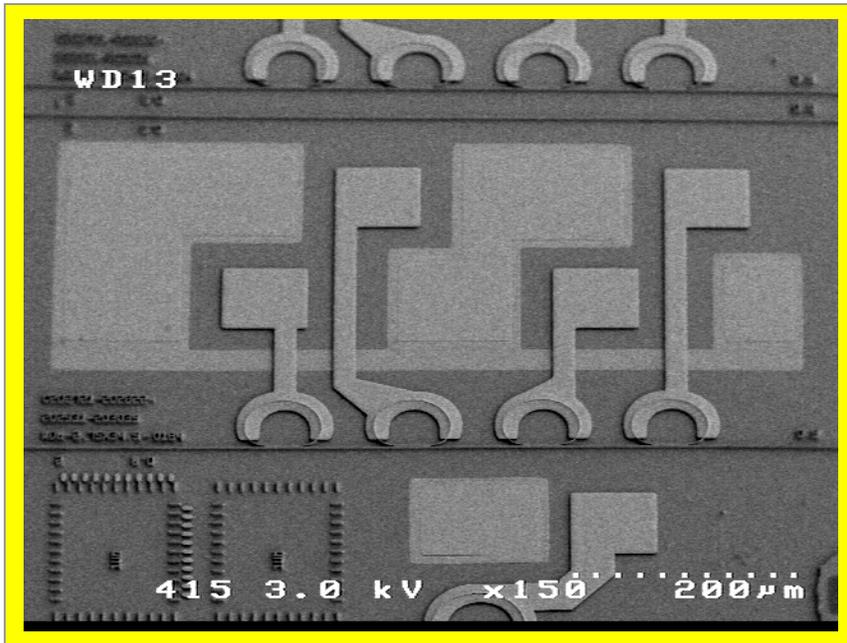
- **Advanced dry etching (ICP)**
- **Low capacitance processes**
- **OMCVD (3 reactors)**
 - **GaAs, InP, GaSb, and GaN**
- **MBE/MOMBE (2 chambers)**
 - **GaAs, GaSb currently**

- **Advanced packaging**
- **Ceramic fabrication**
- **Commerical high-speed IC design group (SiGe)**

- **MEMS foundry**
- **Si foundry**

Concept

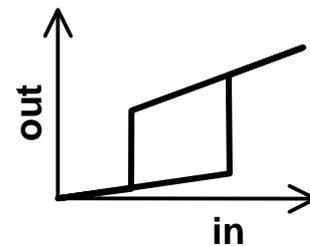
- Ring resonators with tightly confined, deeply etched waveguides.
- Low loss (0.1 cm^{-1}), transparent waveguides



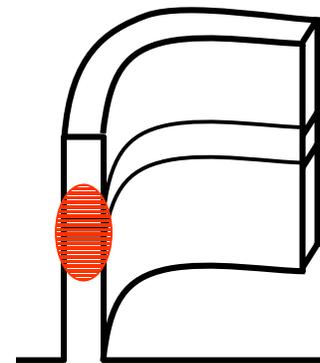
- Nonlinearity enhancement due to power buildup in rings
- Complex functionality on a small scale

Ingredients

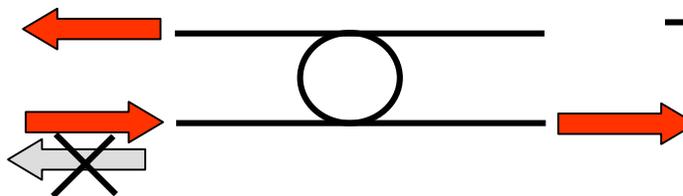
- **Resonant cavities**
 - High power density → enhanced nonlinear effects
 - Wavelength selectivity → bistability



- **Strongly confined waveguides (sub- μm width)**
 - High power density
 - Tight bends, small size → compact integration

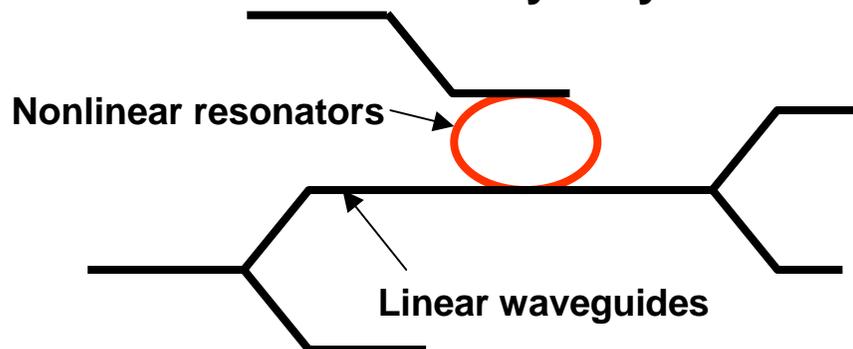


- **Ring resonators**
 - Unidirectional



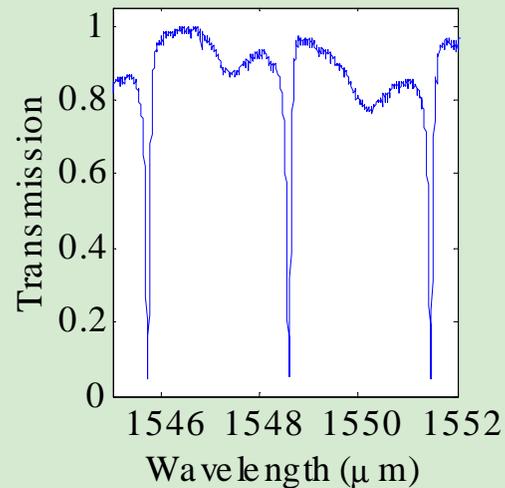
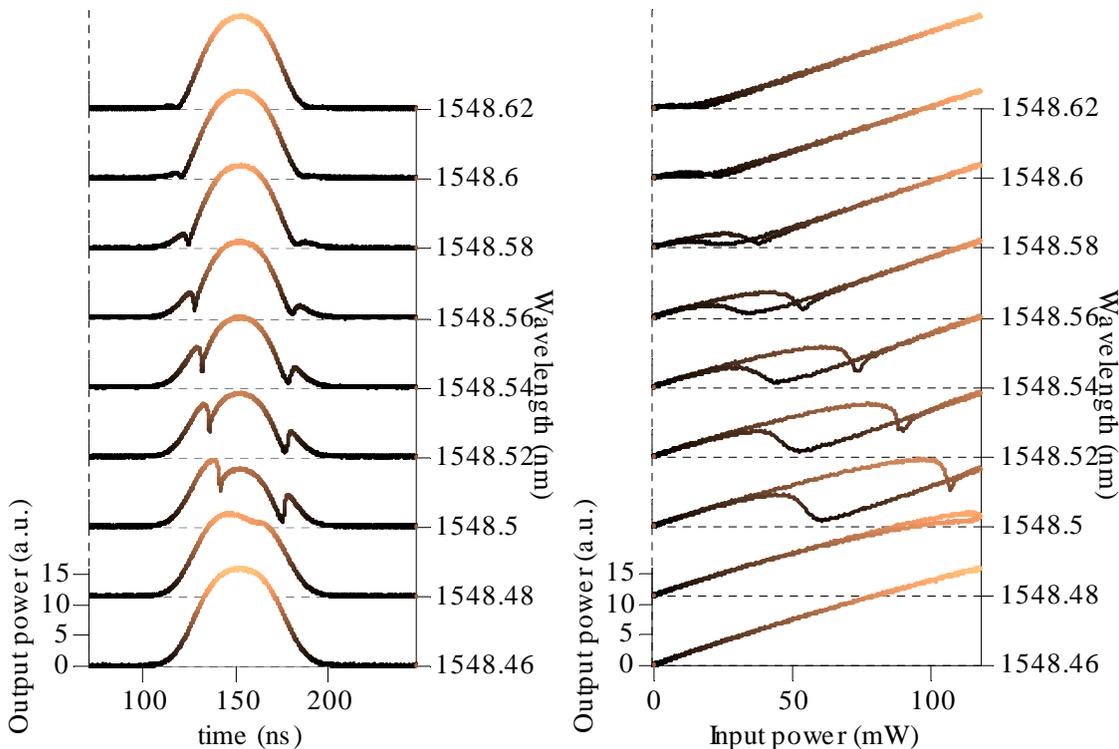
Circuits

- **Ring resonator with high finesse:** → large power enhancement
→ nonlinearity only in resonator



- **Bistability and memory:**
 - photonic logic
 - buffering
 - optical switching
- **Wavelength selectivity:**
 - λ -selective 2R regeneration
 - selective λ -conversion

Demonstration of Bistability in Ring Microresonators



CW transmission (low power)

Periphery: 200 μm

Waveguide width: 1 μm

Q = 20,000

Finesse = 35

**Bistability observed with 50 nsec input pulses
→ non-thermal, carrier induced effect**

100 psec storage time per ring – 1.6e7 psec cm⁻²

